

In the specification, on page 2, third full paragraph:

However, because of various compositions available for the target 15 material and required adaptation to the recent size increase, there have started to appear such cases where only the structure modification provided by devising the method for producing target materials cannot sufficiently suppress the arcing phenomenon and the splash phenomenon. For example, when the material quality of the sputtering target material is a composite material or the like, it cannot always be realized to a sufficiently satisfactory level to disperse dispersion particles in the matrix homogeneously and finely only by resorting to improvement of the production method (see, for example, Patent Document 1). Patent Document 1: Japanese Patent Laid-Open No. 2003-3258).